



Koh Young Highlighting Dimensional Metrology & Inspection Solutions at the Binghamton University Electronics Packaging Symposium in Niskayuna, NY

Atlanta, GA – Koh Young, the industry leader in True 3D™ measurement-based dimensional metrology and inspection solutions, is proud to announce its sponsorship and participation in the 36th Annual Electronics Packaging Symposium (EPS), hosted at the GE Aerospace Research Campus in Niskayuna, New York, on September 03-04, 2025. Organized by the Binghamton University Integrated Electronics Engineering Center (IEEC), EPS brings together thought leaders from industry, academia, and government to share the latest advances in electronic packaging, assembly, and reliability.

The two-day program will feature keynote addresses, technical sessions, and panel discussions covering heterogeneous integration, advanced materials, system reliability, thermal management, and additive manufacturing. Attendees will gain insight into emerging trends and manufacturing challenges across defense, aerospace, automotive, semiconductor, and high-performance computing applications.

As an exhibitor, Koh Young will showcase how its AI-powered True 3D dimensional metrology and inspection solutions are helping manufacturers meet the exacting demands of advanced packaging and semiconductor processes. From wafer-level to system-in-package measurement, Koh Young's technology delivers accurate, repeatable data that enables smarter process control, higher yields, and zero-defect production goals.

Dimensional Metrology for Advanced Packaging

Koh Young's Meister Series is engineered specifically for advanced packaging applications such as system-in-package (SiP), wafer-level packaging (WLP), and die stacking. These systems provide ultra-high-resolution inspection capabilities to handle the smallest features and tightest tolerances in next-generation designs. Complementing the Meister series, ZenStar delivers wafer-level dimensional metrology to detect and measure critical parameters at the earliest possible stage, ensuring that only known-good components move forward in the process. Together, these solutions help manufacturers maintain tight process windows, improve yield, and reduce costly rework.



"Advanced packaging technologies are driving rapid innovation in electronics manufacturing, but they also introduce new complexities in process control and quality assurance," said Joel Scutchfield, General Manager at Koh Young America. *"EPS offers a valuable opportunity to connect with engineers, researchers, and decision makers to demonstrate how our True 3D solutions can help them overcome these challenges and accelerate innovation."*

In addition to networking with attendees, Koh Young will be available to discuss real-world case studies and technology roadmaps that address next-generation packaging needs. The exhibition floor will provide a hands-on look at the tools and solutions shaping the future of electronics manufacturing.

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About Koh Young Technology, Inc.

Founded in 2002, Koh Young Technology transformed the inspection market with the industry's first 3D Solder Paste Inspection (SPI) system using patented dual-projection Moiré technology. Today, Koh Young is the global leader in True3D™ measurement-based SPI and Automated Optical Inspection (AOI) solutions for electronics manufacturing. Building on its core True3D™ technology, Koh Young has expanded its capabilities to address complex inspection challenges, including machined parts, press-fit and through-hole pins, conformal coatings, dispensed materials, and semiconductor packaging. Through continuous innovation and a customer-focused R&D approach, the company has earned the trust of nearly 4,000 customers worldwide and maintains the dominant global market share with over 25,000 systems installed. Headquartered in Korea with regional offices across the globe, Koh Young provides local sales and support to stay close to its markets and growing user base. Electronics manufacturers around the world rely on Koh Young to deliver reliable inspection, actionable process insight, and a pathway to a smarter factory. Learn more at www.kohyoung.com or on its regional website www.kohyoungamerica.com.